

## Memory Compatibility Testing:

The objective of the memory compatibility testing program is to ensure compliance of different memory modules with the MOBILITY™ RADEON™ 7000 IGP chipset. The modules are tested as to ATI specifications using industry standard testing methods. This testing is not intended to replace the normal OEM module qualification process.

At this time, modules should be submitted to ATI for validation testing.

Please contact [memory@ati.com](mailto:memory@ati.com) should you have any questions or wish to get your modules validated on an ATI reference platform.

### **MOBILITY™ RADEON™ 7000 IGP Compatible DDR333 (PC2700) 184 Pin Unbuffered DIMM memory Modules**

<u>Buffalo</u>					
Density	Module Part Number	CL	Loads	Component Organization	Component Vendor & Part Number
512 MB	DN333-A512M	2.5	16	32M X 16	Buffalo ME46512823MEK

<u>Elpida</u>					
Density	Module Part Number	CL	Loads	Component Organization	Component Vendor & Part Number
256 MB	EBD26UC6AKSA-6B	2.5	8	16M X 16	Elpida EDD2516AKTA-6B
512 MB	EBD52UD6ADSA-6B	2.5	8	32M X 16	Elpida EDD5116ADTA-6B
1 GB	EBD11UD8ABDA-6B	2.5	16	64M X 8	Elpida EDD5108ABNA-6B
1 GB	EBD11UD8ADDA-6B	2.5	16	64M X 8	Elpida EDD5108ADNA-6B

<u>Hynix</u>					
Density	Module Part Number	CL	Loads	Component Organization	Component Vendor & Part Number
128 MB	HYMD216M646A6-J	2.5	4	16M X 16	Hynix HY5DU561622AT-J
256 MB	HYMD232M646A8-J	2.5	8	32M X 8	Hynix HY5DU56822AT-J

Micron					
Density	Module Part Number	CL	Loads	Component Organization	Component Vendor & Part Number
128 MB	MT4VDDT1664HG-335C3	2.5	4	16M X 16	Micron MT46V16M16-6T
256 MB	MT8VDDT3264HG-335C2	2.5	8	32M X 8	Micron MT46V32M8-6T
256 MB	MT8VDDT3264HG-335C3	2.5	8	16M X 16	Micron MT46V16M16-6T
512 MB	MT8VDDT6464HDG-335C1	2.5	8	32M X 16	Micron MT46V32M16TG-6TC
512 MB	MT16VDDF6464HG-335C2	2.5	16	32M X 8	Micron MT46V32M8FG-6

Mosel Vitelic					
Density	Module Part Number	CL	Loads	Component Organization	Component Vendor & Part Number
256 MB	V826632G24SATG-C0	2.5	8	32M X 8	Mosel Vitelic V58C2256804SAT6
512 MB	V826664G24SASG-C0	2.5	16	32M X 8	Mosel Vitelic V58C2256804SAS6

Nanya					
Density	Module Part Number	CL	Loads	Component Organization	Component Vendor & Part Number
256 MB	NT256D64SH8BAGM-6K	2.5	8	16M X 16	Nanya NT5DS16M16BT-6K
512 MB	NT512D64S8HBAFM-6K	2.5	16	32M X 8	Nanya NT5DS32M8BF-6K

Qimonda (Formerly Infineon)					
Density	Module Part Number	CL	Loads	Component Organization	Component Vendor & Part Number
128 MB	HYS64D16000GDL-6-B	2.5	4	16M X 16	Qimonda HYB25D256160BT-6
128 MB	HYS64D16000HDL-6-C	2.5	4	16M X 16	Qimonda HYB25D256160CE-6
256 MB	HYS64D32020GDL-6-B	2.5	8	16M X 16	Qimonda HYB25D256160BT-6
256 MB	HYS64D32020HDL-6-C	2.5	8	16M X 16	Qimonda HYB25D256160CE-6
512 MB	HYS64D64020GBDL-6-B	2.5	16	64M X 4	Qimonda HYB25D256800BC-6

Samsung					
Density	Module Part Number	CL	Loads	Component Organization	Component Vendor & Part Number
128 MB	M470L1624DT0-CB3	2.5	4	16M X 16	Samsung K4H561638D-TCB3
128 MB	M470L1624FT0-CB3	2.5	4	16M X 16	Samsung K4H561638F-TCB3
128 MB	M470L1714DT0-CB3	2.5	8	8M X 16	Samsung K4H281638D-TCB3
256 MB	M470L3224DT0-CB3	2.5	8	16M X 16	Samsung K4H561638D-TCB3
256 MB	M470L3224FT0-CB3	2.5	8	16M X 16	Samsung K4H561638F-TCB3
512 MB	M470L6423DN0-CB3	2.5	16	32M X 8	Samsung K4H560838D-NCB3
512 MB	M470L6423EN0-CB3	2.5	16	32M X 8	Samsung K4H560838E-NCB3
1 GB	M470L2923BN0-CB3	2.5	16	64M X 8	Samsung K4H510838B-TCB3